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Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number					
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		PMEG045T050EPD Part Description					
		SMD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
			TEST				
	Pre- and Post-Stress						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		JESD22-A113					
		Bake Tamb = 125 °C	24 hours				
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours				
# A1	Preconditioning	Reflow soldering	3 cycles	810	58300	0	
		MIL-STD-750-1					
	HTRB	M1038 Method A					
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage ^[1]					
# B1	Bias	reverse voltage	1000 hours	116	9280	0	
	тс	JESD22-A104					
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	170	13600	0	
		JESD22-A102					
	AC	Tamb = 121 °C, RH = 100 %					
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0	
<i>"</i> , io die							
	H3TRB	JESD22-A101					
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of					
# A2 alt		rated reverse voltage ^{[1], [2]}	1000 hours	170	13600	0	
		MIL-STD-750 Method 1037					
	IOL	ton = toff, devices powered to insure ΔT_j =					
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	170	13600	0	
	RSH	JESD22-A111					
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	130	3900	0	
	SD						
# C10	Solderability	J-STD-002		363	3630	0	

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9280	0	0.46	2.19E+09
	Beneticity	200	5		21152.05

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